

ABSTRACT

5 A polishing method capable of detecting a polishing endpoint where an upper layer
is polished and a lower layer is exposed, without depending on changes in torque current
and polishing rate is disclosed. The polishing method includes: supplying a polishing
liquid onto a polishing pad on a polishing table while rotating the polishing table; polishing
a workpiece in the presence of the polishing liquid by pressing the workpiece against the
10 polishing pad; irradiating the workpiece with light each time the polishing table makes one
rotation, and generating a spectrum of reflected light from the workpiece; calculating an
index value indicating similarity between the spectrum of the reflected light and an interface
spectrum; and determining a polishing endpoint at which the index value is maximized or
minimized. The interface spectrum is a spectrum of reflected light from a reference
15 workpiece generated when a first film is removed and a second film underlying the first film
is exposed during polishing of the reference workpiece.

FIG. 6